

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4747238

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KOHEI SASAKI	10/30/2017
KEN GOTO	10/26/2017
MASATAKA HIGASHIWAKI	10/30/2017
AKINORI KOUKITU	10/25/2017
YOSHINAO KUMAGAI	11/07/2017
HISASHI MURAKAMI	11/06/2017
RECEIVING PARTY DATA	
Name:	TAMURA CORPORATION
Street Address:	1-19-43 HIGASHI-OIZUMI
Internal Address:	NERIMA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	178-8511
Name:	NATIONAL INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY
Street Address:	4-2-1, NUKUI-KITAMACHI
Internal Address:	KOGANEI-SHI
City:	TOKYO
State/Country:	JAPAN
Postal Code:	184-8795
Name:	NATIONAL UNIVERSITY CORPORATION TOKYO UNIVERSITY OF AGRICULTURE AND TECHNOLOGY
Street Address:	3-8-1, HARUMI-CHO
Internal Address:	FUCHU-SHI
City:	TOKYO
State/Country:	JAPAN
Postal Code:	183-8538
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15559702

PATENT

CORRESPONDENCE DATA**Fax Number:** (516)742-4366*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***Phone:** 516-742-4343**Email:** anna@SSMP.COM**Correspondent Name:** SCULLY SCOTT MURPHY & PRESSER, PC**Address Line 1:** 400 GARDEN CITY PLAZA**Address Line 2:** SUITE 300**Address Line 4:** GARDEN CITY, NEW YORK 11530

ATTORNEY DOCKET NUMBER:	35368
NAME OF SUBMITTER:	PAUL J. ESATTO, JR.
SIGNATURE:	/Paul J. Esatto, Jr./
DATE SIGNED:	12/21/2017
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 6

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**COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN
APPLICATION AND ASSIGNMENT**

As a below named inventor, I hereby declare that:

This declaration the attached application, or
is directed to:

United States application or PCT international application number
15/559,702 filed on September 19, 2017 ; and
entitled: HIGH WITHSTAND VOLTAGE SCHOTTKY BARRIER DIODE.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
application.

I hereby state that I have reviewed and understand the contents of the above-identified application,
including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information
known to me to be material to patentability as defined in 37 CFR 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements and
discoveries (herein referred to as the "Invention") disclosed in the above-identified patent
application;

Whereas, TAMURA CORPORATION, a corporation of Japan, having a place of business at
1-19-43, Higashi-Oizumi, Nerima-ku, Tokyo 178-8511, Japan and NATIONAL INSTITUTE OF
INFORMATION AND COMMUNICATIONS TECHNOLOGY, a corporation of Japan, having
a place of business at 4-2-1, Nukui-Kitamachi, Koganei-shi, Tokyo 184-8795, Japan and
National University Corporation Tokyo University of Agriculture and Technology, a corporation
of Japan, having a place of business at 3-8-1, Harumi-cho, Fuchu-shi, Tokyo, 183-8538, Japan,
desires to acquire, and each undersigned inventor desires to grant to TAMURA
CORPORATION and NATIONAL INSTITUTE OF INFORMATION AND
COMMUNICATIONS TECHNOLOGY and National University Corporation Tokyo University
of Agriculture and Technology, the entire worldwide right, title and interest in and to any and all
patent applications and patents directed thereto;

Now, therefore, in consideration of One Dollar (\$1.00), and other good and valuable
considerations, the receipt of which is hereby acknowledged, each undersigned inventor
("ASSIGNOR") hereby sells, assigns and transfers to TAMURA CORPORATION and
NATIONAL INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY
and National University Corporation Tokyo University of Agriculture and Technology (the
"ASSIGNEE"), its successors, assigns and legal representatives, the entire right, title and interest

for all countries, in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisional, continuing, substitute, reexamination, renewal, reissue and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Commissioner of Patents to issue, in accordance with this assignment, any and all United States Letters Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention to said Assignee, the corporation above named, its successors, assigns and legal representatives; and agreeing to carry out in good faith the intent and purpose of this assignment, the undersigned will, for the United States and all foreign countries, execute all divisional, continuing, substitute, renewal, reissue and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; testify in all legal proceedings; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Legal name of sole or first inventor Kohei Sasaki	
Sole or first inventor's signature <i>Kohei Sasaki</i>	Date 30, Oct. 2017

Legal name of second inventor Ken Goto	
Second inventor's signature <i>Ken Goto</i>	Date 26, Oct. 2017

Legal name of third inventor Masataka Higashiwaki	
Third inventor's signature	Date

Legal name of fourth inventor Akinori Koukitu	
Fourth inventor's signature	Date

Legal name of fifth inventor Yoshinao Kumagai	
Fifth inventor's signature	Date

Legal name of sixth inventor Hisashi Murakami	
Sixth inventor's signature	Date

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INFORMATION AND COMMUNICATIONS TECHNOLOGY, a corporation of Japan, having
a place of business at 4-2-1, Nukui-Kitamachi, Koganei-shi, Tokyo 184-8795, Japan and
National University Corporation Tokyo University of Agriculture and Technology, a corporation
of Japan, having a place of business at 3-8-1, Harumi-cho, Fuchu-shi, Tokyo, 183-8538, Japan,
desires to acquire, and each undersigned inventor desires to grant to TAMURA
CORPORATION and National University Corporation Tokyo University of Agriculture and
Technology, the entire worldwide right, title and interest in and to any and all patent applications
and patents directed thereto;

Now, therefore, in consideration of One Dollar (\$1.00), and other good and valuable
considerations, the receipt of which is hereby acknowledged, each undersigned inventor
("ASSIGNOR") hereby sells, assigns and transfers to TAMURA CORPORATION and
NATIONAL INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY
and National University Corporation Tokyo University of Agriculture and Technology (the
"ASSIGNEE"), its successors, assigns and legal representatives, the entire right, title and interest


for all countries, in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisional, continuing, substitute, reexamination, renewal, reissue and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Commissioner of Patents to issue, in accordance with this assignment, any and all United States Letters Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention to said Assignee, the corporation above named, its successors, assigns and legal representatives; and agreeing to carry out in good faith the intent and purpose of this assignment, the undersigned will, for the United States and all foreign countries, execute all divisional, continuing, substitute, renewal, reissue and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; testify in all legal proceedings; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

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Legal name of sole or first inventor Kohei Sasaki	
Sole or first inventor's signature	Date

Legal name of second inventor Ken Goto	
Second inventor's signature	Date

Legal name of third inventor Masataka Higashiwaki	
Third inventor's signature 	Date 10/30/2017

Legal name of fourth inventor Akinori Koukitu	
Fourth inventor's signature <i>Akinori Koukitu</i>	Date Oct 25, 2017

Legal name of fifth inventor Yoshinao Kumagai	
Fifth inventor's signature <i>Yoshinao Kumagai</i>	Date Nov. 7, 2017

Legal name of sixth inventor Hisashi Murakami	
Sixth inventor's signature <i>Hisashi Murakami</i>	Date Nov. 6, 2017